


NOTES:

1. MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.203 ± 0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QP TECHNOLOGIES FOR DETAILS.
2. FINISH:
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICROINCHES (2.5µm-7.6µm) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1µm-2µm) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Rq)
3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
5. PACKAGE CONFORMS TO JEDEC MO-220

PROPRIETARY AND CONFIDENTIAL
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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: ANGULAR: ±0.5 degree .X = ±0.76 .XX: ±0.05		NAME	DATE	 TITLE: QP-QFN88-10MM-0.40MM		
		DRAWN	D. Abbe	8/10/11				
		CHECKED	S. Swen	8/10/11				
		ENG APPR.	S. Swen	8/10/11				
		COMMENTS:				SIZE B	DWG. NO. 500407	REV A
NEXT ASSY	USED ON	MATERIAL	SEE NOTE 1					
		FINISH	SEE NOTE 2					
APPLICATION		DO NOT SCALE DRAWING		SCALE: 7:1	WEIGHT:	SHEET 1 OF 1		

